L Number	Hits	Search Text	DB	Time stamp
11	1	Search Text	USPAT	2004/06/23 18:59
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16	1		USPAT	2004/06/23 19:00
17	1		USPAT	2004/06/23 19:00
18			USPAT	2004/06/23 19:00
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21	1		USPAT	2004/06/23 19:00
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31	1		USPAT	2004/06/23 19:02
32	1		USPAT	2004/06/23 19:02
33	1		USPAT	2004/06/23 19:03
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36	1		USPAT	2004/06/23 19:03
37	1	·	USPAT	2004/06/23 19:03
38	1	<u>'</u>	USPAT	2004/06/23 19:03
39	1		USPAT	2004/06/23 19:03
40	Ī		USPAT	2004/06/23 19:04
41	İ		USPAT	2004/06/23 19:04
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42	0	""" " " " " " " " " " " " " " " " " "	USPAT	2004/06/23 19:04
43	54	"5994166"	USPAT	2004/06/23 19:04
46	383	257/777 and (solder or ball or bump) and	USPAT	2004/06/23 21:16
		(capacitor or resistor)		
47	26	(257/777 or 257/686) and (solder or ball	USPAT	2004/06/23 21:19
		or bump) and (silicon or "Si") near (die		
		or chip or semiconductor or IC) with		
		memory		
48	207	(257/777 or 257/686) and (solder or ball	USPAT	2004/06/23 21:19
10	201	or bump) and (silicon or "Si") near (die	\ \tag{2}	
	-	or chip or semiconductor or IC) and memory	1100000	0004/06/20 14:01
-	5		USPAT	2004/06/22 14:21
		or 5578871.pn. or 5371044.pn.		
-	1	"6639306"	USPAT	2004/06/22 14:25
-	0	"20010033011"	USPAT	2004/06/22 14:23
-	1	"20010033011"	USPAT;	2004/06/22 14:23
			US-PGPUB	
_	1		USPAT	2004/06/22 14:24
_	l i		USPAT	2004/06/22 14:24
1_	1		USPAT	2004/06/22 14:24
1 -				2004/06/22 14:24
-	1		USPAT	
-	1		USPAT	2004/06/22 14:25
-	1		USPAT	2004/06/22 14:25
-	464	(semiconductor or die or chip or IC) and	USPAT	2004/06/22 15:07
	1	(die near pad or paddle) with (protru\$4 or		
		tab)		
_	10	(semiconductor or die or chip or IC) and	USPAT	2004/06/22 14:46
		(die near pad or paddle) with (indenta\$4)		
<b>I</b> _	5894	(semiconductor or die or chip or IC) and	USPAT	2004/06/22 14:47
-	5894		OSFAI	2004/00/22 14:4/
ł		(lead) with (protru\$4 or tab or		
1		indentat\$3)	i	1 1
-	909	((semiconductor or die or chip or IC) and	USPAT	2004/06/22 14:48
		(lead) with (protru\$4 or tab or		
		indentat\$3)) and 438/\$.ccls.	1	
_	1		USPAT	2004/06/22 14:49
1_	1		USPAT	2004/06/22 14:50
			USPAT	2004/06/22 14:50
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_	1		USPAT	2004/06/22 14:51
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L <u>-</u>	1		USPAT	2004/06/22 14:51

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-	1		USPAT	2004/06/22 14:55
-	1		USPAT	2004/06/22 14:55
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	1			2004/06/22 14:55
_	1		USPAT	
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-	1		USPAT	2004/06/22 14:55
_	1		USPAT	2004/06/22 14:56
i _	1		USPAT	2004/06/22 14:56
	1			2004/06/22 14:56
_	1		USPAT	
-	1		USPAT	2004/06/22 14:56
_	1		USPAT	2004/06/22 14:56
_	1		USPAT	2004/06/22 14:57
_	1		USPAT	2004/06/22 14:57
	1 1		· ·	2004/06/22 14:57
_			USPAT	l ' '
_	112	(semiconductor or die or chip or IC) and	JPO	2004/06/22 15:16
		(die near pad or paddle) with (protru\$4 or		
		tab)		
_	3151	257/666	USPAT	2004/06/22 15:18
	! .			
-	1		USPAT	2004/06/22 15:19
-	1		USPAT	2004/06/22 15:19
_	1		USPAT	2004/06/22 15:19
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-	1		USPAT	2004/06/22 15:19
-	1		USPAT	2004/06/22 15:19
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_	1		USPAT	2004/06/22 15:19
-	1		USPAT	2004/06/22 15:20
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i _	1		USPAT	2004/06/22 15:21
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-	1		USPAT	2004/06/22 15:21
-	1		USPAT	2004/06/22 15:21
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_	1		USPAT	2004/06/22 15:24
i -	1		USPAT	2004/06/22 15:26
-	1		USPAT	2004/06/22 15:26
_	30	"5214307"	USPAT	2004/06/22 15:31
_	1		USPAT	2004/06/22 15:29
T	1			1 ' ' 1
_	1		USPAT	2004/06/22 15:29
i -	1		USPAT	2004/06/22 15:31
-	11	"5864174"	USPAT	2004/06/22 15:36
_	2233	257/676	USPAT	2004/06/22 15:36
_	1940	257/676 and (wir\$3)	USPAT	2004/06/22 15:38
1_	1	20., 5.0 4114 (11245)		
-	1		USPAT	2004/06/22 15:42
-	1		USPAT	2004/06/22 15:43
-	1		USPAT	2004/06/22 15:43
-	1		USPAT	2004/06/22 15:43
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-	_		USPAT	2004/06/22 17:18
-	1		USPAT	2004/06/22 17:19
-	1		USPAT	2004/06/22 17:19
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_	ĺ		USPAT	2004/06/22 17:19
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-	1		USPAT	2004/06/22 17:19
-	1		USPAT	2004/06/22 17:20
-	1		USPAT	2004/06/22 17:20
_	943	438/112	USPAT;	2004/06/22 17:46
			US-PGPUB;	
1			· ·	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	363	438/117	USPĀT;	2004/06/22 18:04
			US-PGPUB;	,, 10.04
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			EPO; JPO;	
			DERWENT;	
	l		IBM TDB	
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	1.610	420/102	TTODAM.	2004/06/22 10:46
-	1618	438/123	ÜSPAT;	2004/06/22 18:46
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	!		IBM_TDB	<i>, ,</i>
-	1187	438/124	USPAT;	2004/06/22 19:08
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	:		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1628	438/127	USPAT;	2004/06/22 19:27
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	/ /
-	3151	257/666	USPAT	2004/06/22 19:28
-	3167	257/676	USPAT;	2004/06/22 19:54
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			EPO; JPO;	
			DERWENT;	
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-	4566	257/787	USPAT;	2004/06/23 11:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		055 /550	IBM_TDB	0004/06/00 11 00
-	3904	257/778	USPAT;	2004/06/23 11:32
			US-PGPUB;	
1			EPO; JPO;	1
			DERWENT;	
	2200	257 /770	IBM_TDB USPAT	2004/06/23 11:32
-	3388	257/778		2004/06/23 11:32
-	2754	257/778 and solder	USPAT	2004/06/23 11:32
<del>-</del>	610	257/778 and solder with (big\$3 or larg\$2)	USPAT	2004/06/23 11:55
-	1327	257/777 and solder	USPAT USPAT	2004/06/23 11:36
_	1585	257/777 and (solder or ball or bump) 257/777 and (solder or ball or bump)	JPO	2004/06/23 19:16
-	45	257/686 and (solder or ball or bump)	USPAT; JPO	2004/06/23 12:58
-	1622	· · · · · · · · · · · · · · · · · · ·	USPAT; JPO	
-	9	"6297960"	USPAI	2004/06/23 15:56

L Number	Hits	Search Text	DB	Time stamp
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23	1		USPAT	2004/06/23 19:01
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27	1		USPAT	2004/06/23 19:01
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38	- 1		USPAT	2004/06/23 19:03
39	1		USPAT	2004/06/23 19:03
40	1		USPAT	2004/06/23 19:03
1				I
41	1		USPAT	2004/06/23 19:04
42	0	NEO04166H	USPAT	2004/06/23 19:04
43	54	"5994166"	USPAT	2004/06/23 19:04
46	383	257/777 and (solder or ball or bump) and	USPAT	2004/06/23 21:16
		(capacitor or resistor)		
47	26	(257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die or chip or semiconductor or IC) with	USPAT	2004/06/23 21:19
48	207	memory (257/777 or 257/686) and (solder or ball or bump) and (silicon or "Si") near (die	USPAT	2004/06/23 21:19
-	5	or chip or semiconductor or IC) and memory 6081029.pn. or 5942794.pn. or 5623162.pn. or 5578871.pn. or 5371044.pn.	USPAT	2004/06/22 14:21
-	1	"6639306"	USPAT	2004/06/22 14:25
-	0	"20010033011"	USPAT	2004/06/22 14:23
-	1	"20010033011"	USPAT; US-PGPUB	2004/06/22 14:23
-	1		USPAT	2004/06/22 14:24
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_	1		USPAT	2004/06/22 14:25
_	1		USPAT	2004/06/22 14:25
_	464	(semiconductor or die or chip or IC) and (die near pad or paddle) with (protru\$4 or	USPAT	2004/06/22 14:23
-	10	tab) (semiconductor or die or chip or IC) and (die near pad or paddle) with (indenta\$4)	USPAT	2004/06/22 14:46
_	5894	(semiconductor or die or chip or IC) and (lead) with (protru\$4 or tab or	USPAT	2004/06/22 14:47
-	909	<pre>indentat\$3) ((semiconductor or die or chip or IC) and (lead) with (protru\$4 or tab or indentat\$3)) and 438/\$.ccls.</pre>	USPAT	2004/06/22 14:48
	1	Indentatys); and 450/9.0018.	IISDAT	2004/06/22 14:49
-	1		USPAT	
<del>-</del>	1		USPAT	2004/06/22 14:50
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-	1		USPAT	2004/06/22 14:51
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_	1		USPAT	2004/06/22 14:55
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_	1		USPAT	2004/06/22 14:55
_			USPAT	2004/06/22 14:56
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-	1		USPAT	2004/06/22 14:56
-	1		USPAT	2004/06/22 14:56
_	1		USPAT	2004/06/22 14:57
_	1		USPAT	2004/06/22 14:57
_	1		USPAT	2004/06/22 14:57
1 _	112	(somiconductor on die on chin on TC) and	JPO	2004/06/22 15:16
<del>-</del>	112	(semiconductor or die or chip or IC) and	UPO	2004/00/22 13:16
		(die near pad or paddle) with (protru\$4 or		
		tab)		
-	3151	257/666	USPAT	2004/06/22 15:18
-	1		USPAT	2004/06/22 15:19
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-	1			2004/06/22 15:19
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-	1		USPAT	2004/06/22 15:19
-	1		USPAT	2004/06/22 15:19
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-	1		USPAT	2004/06/22 15:20
-	1		USPAT	2004/06/22 15:21
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-	1		USPAT	2004/06/22 15:26
† <b>-</b>	1		USPAT	2004/06/22 15:26
1_	30	"5214307"	USPAT	2004/06/22 15:31
l _	1	3211301	USPAT	2004/06/22 15:29
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-	1			2004/06/22 15:29
-	1		USPAT	
-	11	"5864174"	USPAT	2004/06/22 15:36
-	2233	257/676	USPAT	2004/06/22 15:36
-	1940	257/676 and (wir\$3)	USPAT	2004/06/22 15:38
_	1		USPAT	2004/06/22 15:42
	1		USPAT	2004/06/22 15:43
_	1		USPAT	2004/06/22 15:43
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-	1		USPAT	2004/06/22 15:43
-	1		USPAT	2004/06/22 17:18
-	1		USPAT	2004/06/22 17:19
-	1		USPAT	2004/06/22 17:19
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1 -				2004/06/22 17:19
-	1		USPAT	
1 -	1		USPAT	2004/06/22 17:20
-	1		USPAT	2004/06/22 17:20
-	943	438/112	USPAT;	2004/06/22 17:46
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-	363	438/117	USPAT;	2004/06/22 18:04
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-	1618	438/123	USPAT;	2004/06/22 18:46
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-	1187	438/124	USPAT;	2004/06/22 19:08
			US-PGPUB;	
			EPO; JPO;	İ
			DERWENT;	
			IBM_TDB	
-	1628	438/127	USPAT;	2004/06/22 19:27
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3151	257/666	USPAT	2004/06/22 19:28
-	3167	257/676	USPAT;	2004/06/22 19:54
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			DERWENT;	
			IBM_TDB	
-	4566	257/787	USPAT;	2004/06/23 11:29
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/00 44 00
-	3904	257/778	USPAT;	2004/06/23 11:32
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2200	0.53 /330	IBM TDB	2004/06/22 11:22
-	3388	257/778	USPAT	2004/06/23 11:32 2004/06/23 11:32
-	2754		USPAT USPAT	2004/06/23 11:32
_	610	257/778 and solder with (big\$3 or larg\$2) 257/777 and solder	USPAT	2004/06/23 11:55
-	1327 1585	257/777 and (solder or ball or bump)	USPAT	2004/06/23 11:36
-	1585	257/777 and (solder or ball or bump)	JPO	2004/06/23 19:16
_	1622	257/777 and (solder or ball or bump)	USPAT; JPO	2004/06/23 12:58
<u>-</u>	1622	257/686 and (Solder or ball or bump)	USPAT; JPO	2004/06/23 12:36
1 -	1 9	0237300	LOSPAI	Z004/00/Z3 I3:30